

ABSTRACT

In a compression-bond-connection substrate having a configuration wherein a plurality of wiring layers are formed, elevated compensation patterns having substantially the same thickness as that of backside wiring patterns are formed in positions corresponding to the backsides of substrate-side terminals to be conductively connected to opposing-side terminals on a compression-bonding-side surface of the compression-bond-connection substrate. Since uniform pressure is exerted on the substrate-side terminals when pressure is applied in compression-bonding, a highly reliable compression-bonding connected assembly can be stably obtained.